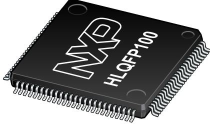
SOT1570-6

HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.4 mm body

3 January 2024 Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HLQFP100
Package style descriptive code	HLQFP (thermal enhanced low profile quad flat package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	07-09-2023
Manufacturer package code	98ASA01897D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	14	-	mm
package width	-	14	-	mm
seated height	-	1.4	1.6	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	100	-	

2 Package outline

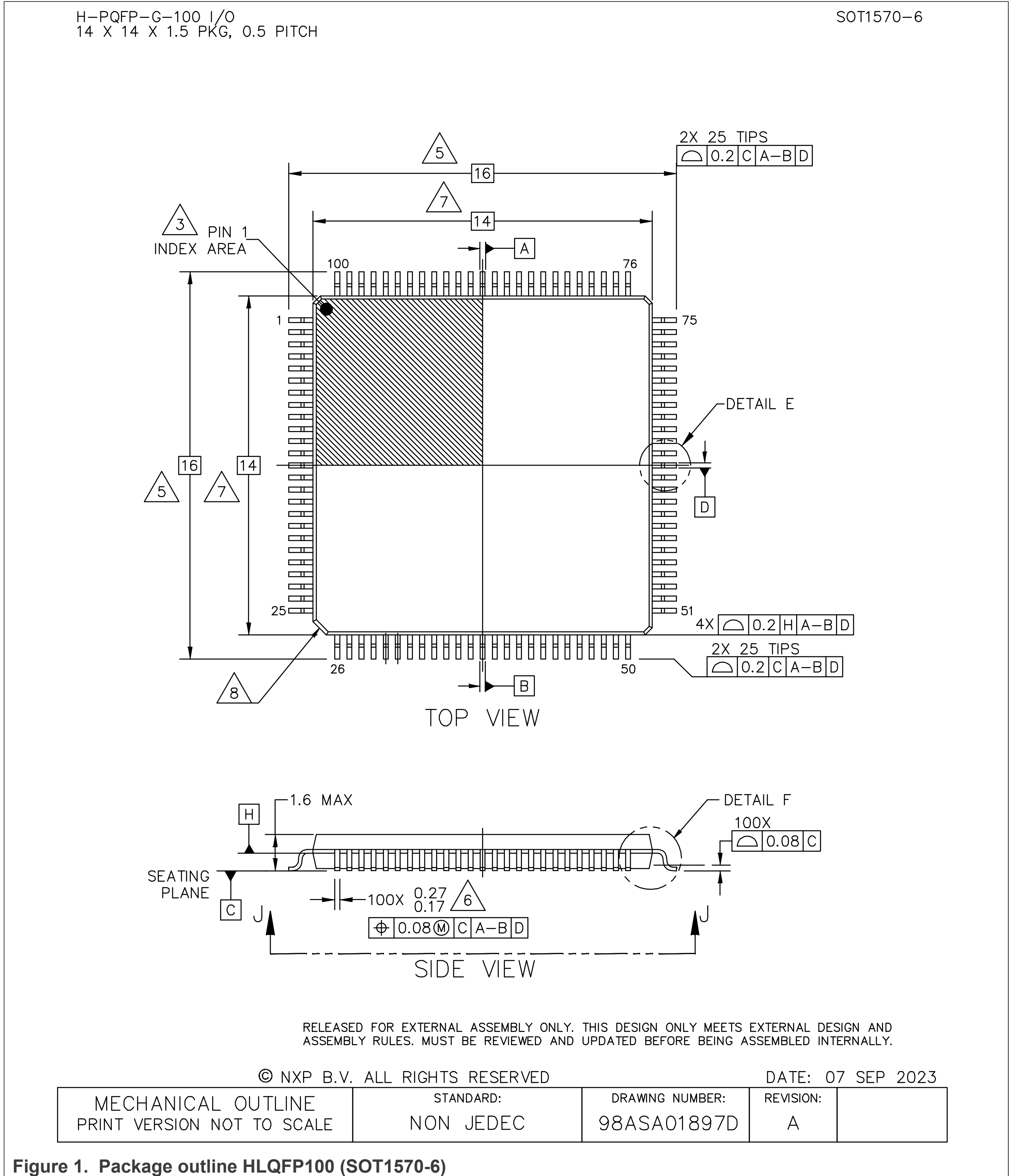


Figure 1. Package outline HLQFP100 (SOT1570-6)

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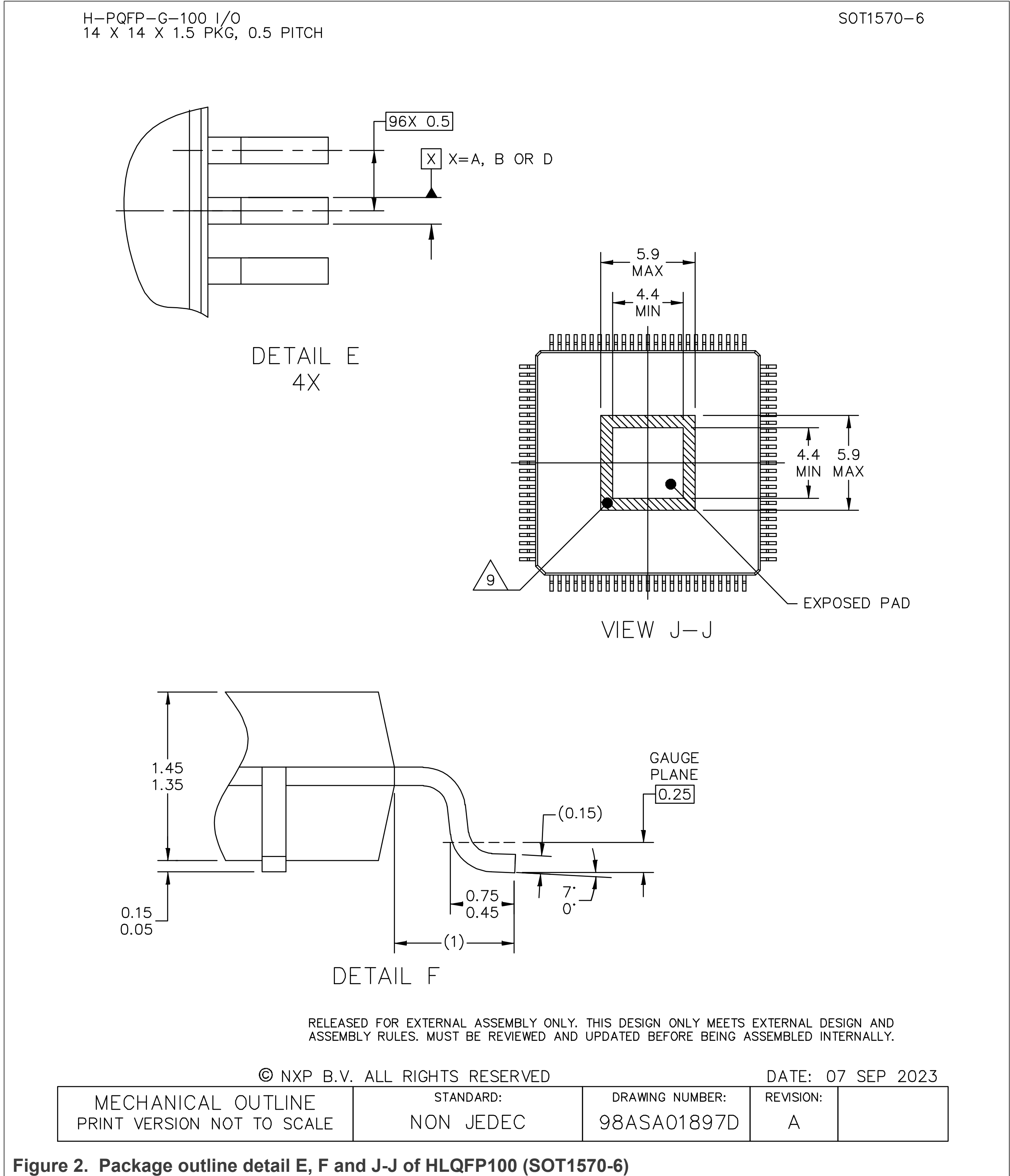

Figure 2. Package outline detail E, F and J-J of HLQFP100 (SOT1570-6)

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3 Soldering

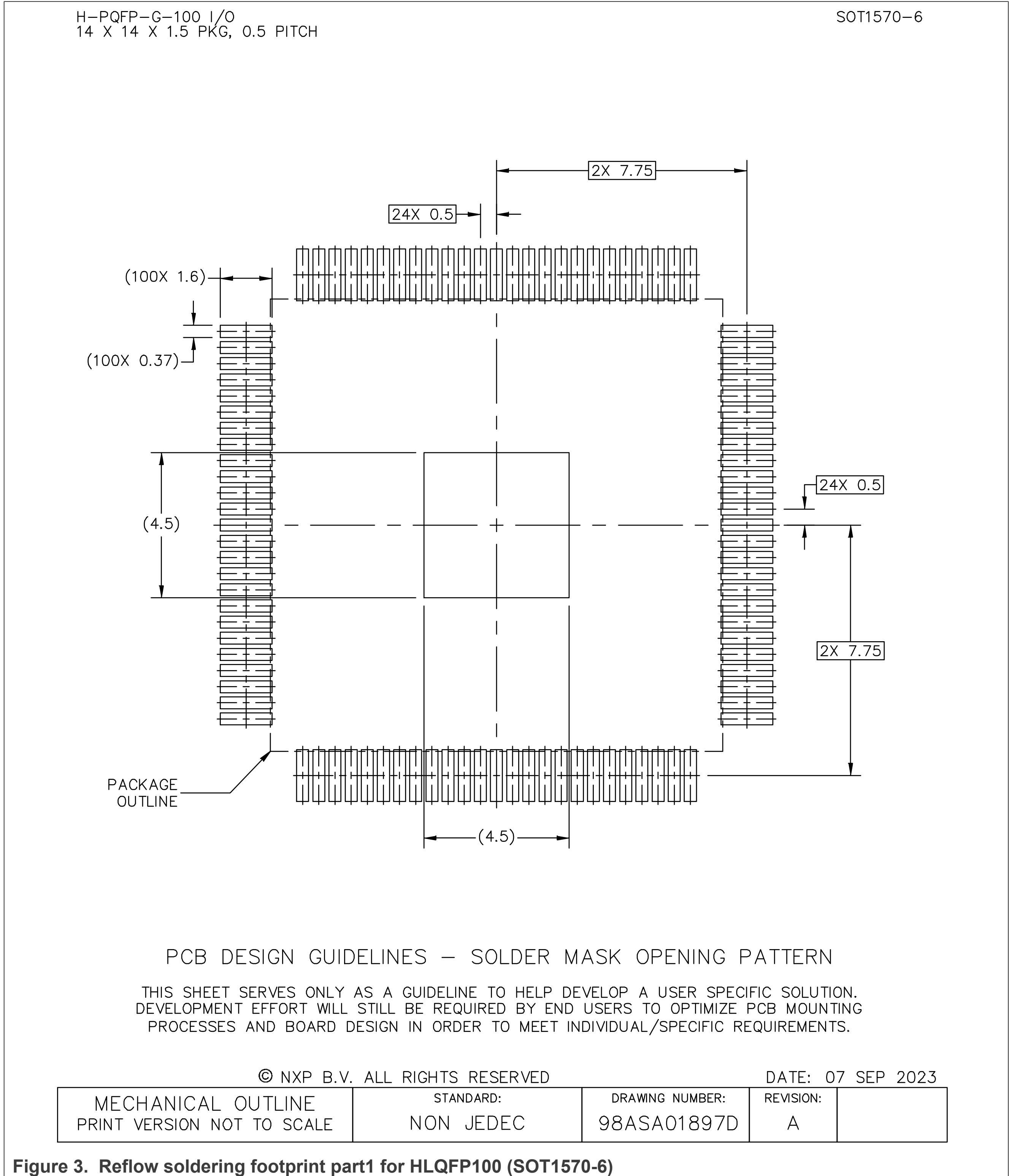

Figure 3. Reflow soldering footprint part1 for HLQFP100 (SOT1570-6)

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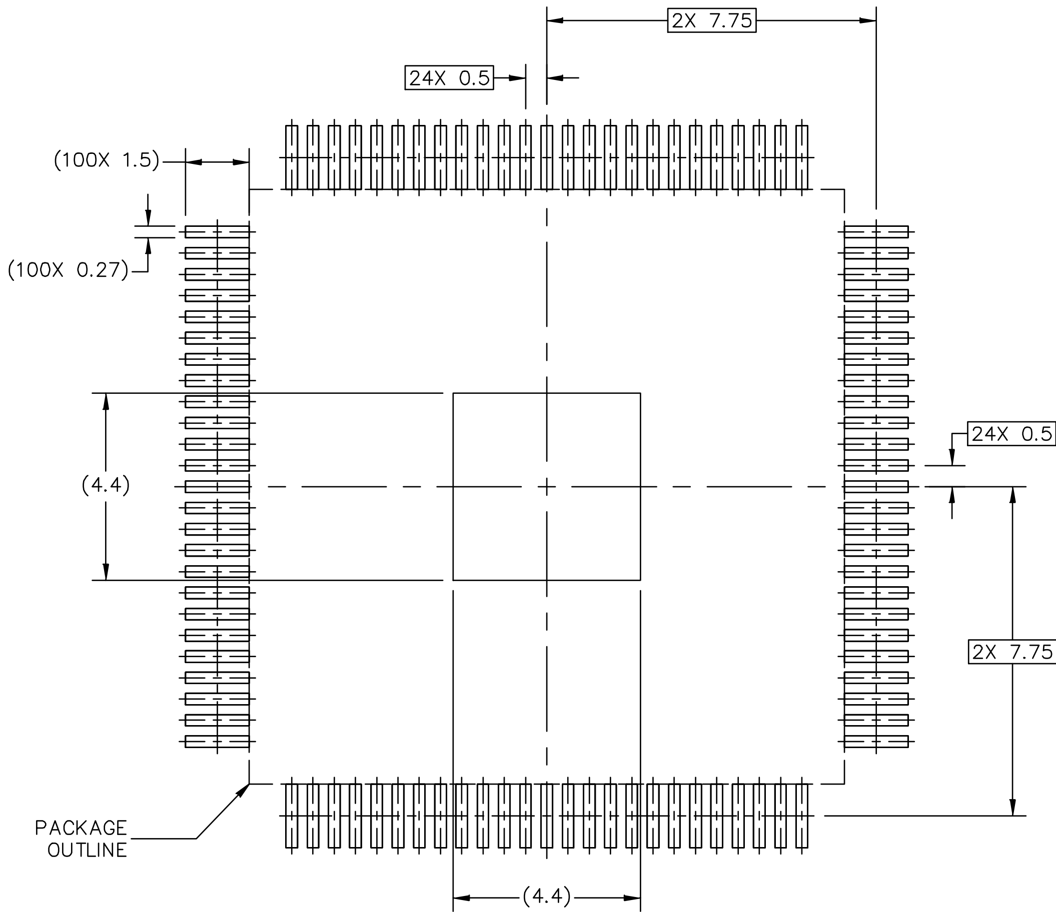
H–PQFP–G–100 I/O
14 X 14 X 1.5 PKG, 0.5 PITCH

SOT1570–6



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.

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DATE: 07 SEP 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01897D	REVISION: A	

Figure 4. Reflow soldering footprint part2 for HLQFP100 (SOT1570-6)

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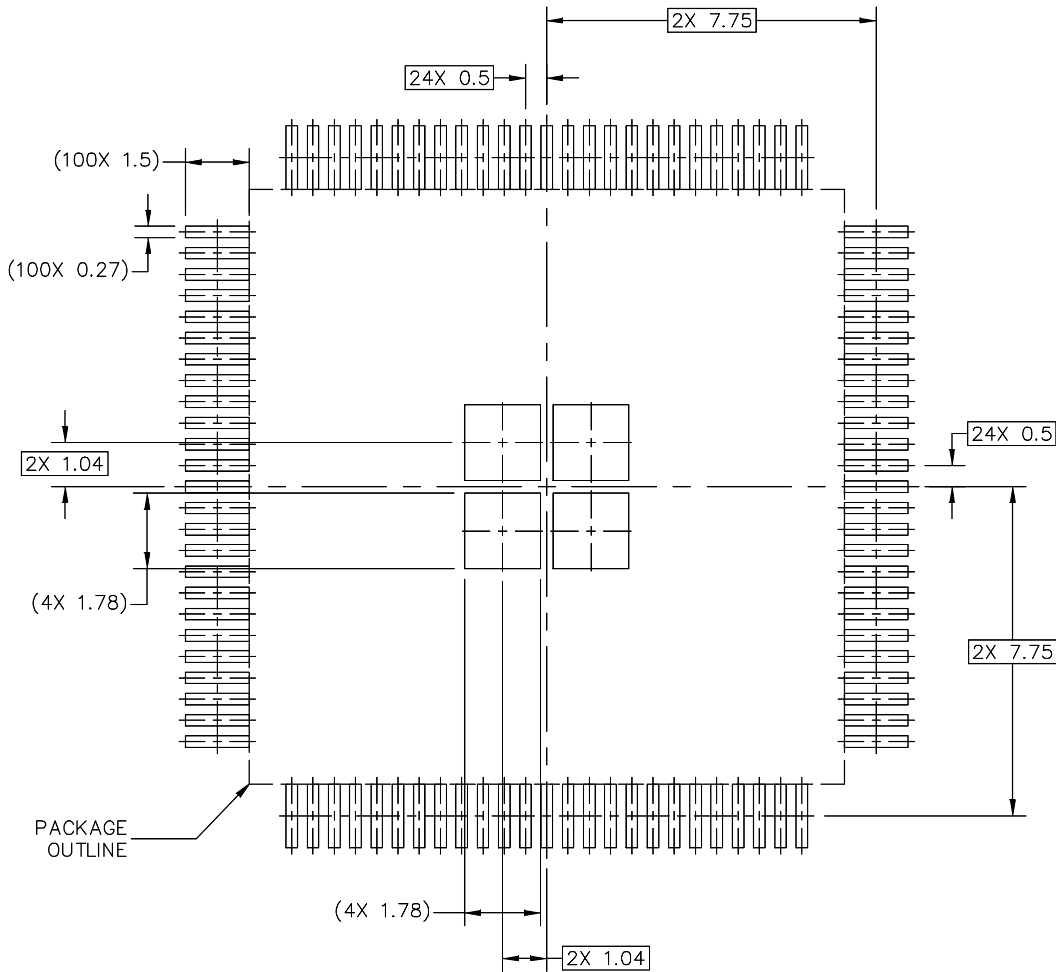
H-PQFP-G-100 I/O
14 X 14 X 1.5 PKG, 0.5 PITCH

SOT1570-6



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01897D	REVISION: A	

Figure 5. Reflow soldering footprint part3 for HLQFP100 (SOT1570-6)

H-PQFP-G-100 I/O
14 X 14 X 1.5 PKG, 0.5 PITCH

SOT1570-6

NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. (△) PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. DATUMS A, B AND D TO BE DETERMINED AT DATUM PLANE H.
5. (△) DIMENSION TO BE DETERMINED AT SEATING PLANE C.
6. (△) THIS DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL NOT CAUSE THE LEAD WIDTH TO EXCEED THE UPPER LIMIT BY MORE THAN 0.08MM AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD SHALL NOT BE LESS THAN 0.07MM.
7. (△) THIS DIMENSION DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.25MM PER SIDE. THIS DIMENSION IS MAXIMUM PLASTIC BODY SIZE DIMENSION INCLUDING MOLD MISMATCH.
8. (△) EXACT SHAPE OF EACH CORNER IS OPTIONAL.
9. (△) HATCHED AREA TO BE KEEP OUT ZONE FOR PCB ROUTING.

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DATE: 07 SEP 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01897D	REVISION: A	

Figure 6. Package outline note HLQFP100 (SOT1570-6)

4 Legal information

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HLQFP100, plastic, thermal enhanced low profile quad flat package; 100 terminals; 0.5 mm pitch; 14 mm x 14 mm x 1.4 mm body

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